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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	3
Program Memory Size	384B (256 x 12)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic10f200-i-p

Email: info@E-XFL.COM

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Pin Diagrams



FIGURE 2: 8-PIN PDIP



FIGURE 3: 8-PIN DFN



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1.0 GENERAL DESCRIPTION

The PIC10F200/202/204/206 devices from Microchip Technology are low-cost, high-performance, 8-bit, fully-static, Flash-based CMOS microcontrollers. They employ a RISC architecture with only 33 single-word/ single-cycle instructions. All instructions are single cycle (1 μ s) except for program branches, which take two cycles. The PIC10F200/202/204/206 devices deliver performance in an order of magnitude higher than their competitors in the same price category. The 12-bit wide instructions are highly symmetrical, resulting in a typical 2:1 code compression over other 8-bit microcontrollers in its class. The easy-to-use and easy to remember instruction set reduces development time significantly.

The PIC10F200/202/204/206 products are equipped with special features that reduce system cost and power requirements. The Power-on Reset (POR) and Device Reset Timer (DRT) eliminate the need for external Reset circuitry. INTRC Internal Oscillator mode is provided, thereby preserving the limited number of I/O available. Power-Saving Sleep mode, Watchdog Timer and code protection features improve system cost, power and reliability.

The PIC10F200/202/204/206 devices are available in cost-effective Flash, which is suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in Flash programmable microcontrollers, while benefiting from the Flash programmable flexibility.

The PIC10F200/202/204/206 products are supported by a full-featured macro assembler, a software simulator, an in-circuit debugger, a 'C' compiler, a low-cost development programmer and a full featured programmer. All the tools are supported on IBM[®] PC and compatible machines.

1.1 Applications

The PIC10F200/202/204/206 devices fit in applications ranging from personal care appliances and security systems to low-power remote transmitters/receivers. The Flash technology makes customizing application programs (transmitter codes, appliance settings, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make these microcontrollers well suited for applications with space limitations. Low cost, low power, high performance, ease-of-use and I/O flexibility make the PIC10F200/202/204/206 devices very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, logic and PLDs in larger systems and coprocessor applications).

		PICTUF200	PICTUF202	PICTUF204	PICTUEZ00
Clock	Maximum Frequency of Operation (MHz)	4	4	4	4
Memory	Flash Program Memory	256	512	256	512
	Data Memory (bytes)	16	24	16	24
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0	TMR0
	Wake-up from Sleep on Pin Change	Yes	Yes	Yes	Yes
	Comparators	0	0	1	1
Features	I/O Pins	3	3	3	3
	Input-Only Pins	1	1	1	1
	Internal Pull-ups	Yes	Yes	Yes	Yes
	In-Circuit Serial Programming [™]	Yes	Yes	Yes	Yes
	Number of Instructions	33	33	33	33
	Packages	6-pin SOT-23 8-pin PDIP, DFN			

TABLE 1-1: PIC10F200/202/204/206 DEVICES

The PIC10F200/202/204/206 devices have Power-on Reset, selectable Watchdog Timer, selectable code-protect, high I/O current capability and precision internal oscillator.

The PIC10F200/202/204/206 devices use serial programming with data pin GP0 and clock pin GP1.



3.1 Clocking Scheme/Instruction Cycle

FIGURE 3-3:

The clock is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the PC is incremented every Q1 and the instruction is fetched from program memory and latched into the instruction register in Q4. It is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-3 and Example 3-1.

CLOCK/INSTRUCTION CYCLE

3.2 Instruction Flow/Pipelining

An instruction cycle consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute take another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the PC to change (e.g., GOTO), then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the PC incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles, since the fetch instruction is "flushed" from the pipeline, while the new instruction is being fetched and then executed.

4.0 MEMORY ORGANIZATION

The PIC10F200/202/204/206 memories are organized into program memory and data memory. Data memory banks are accessed using the File Select Register (FSR).

4.1 Program Memory Organization for the PIC10F200/204

The PIC10F200/204 devices have a 9-bit Program Counter (PC) capable of addressing a 512 x 12 program memory space.

Only the first 256 x 12 (0000h-00FFh) for the PIC10F200/204 are physically implemented (see Figure 4-1). Accessing a location above these boundaries will cause a wraparound within the first 256 x 12 space (PIC10F200/204). The effective Reset vector is at 0000h (see Figure 4-1). Location 00FFh (PIC10F200/204) contains the internal clock oscillator calibration value. This value should never be overwritten.

FIGURE 4-1:

PROGRAM MEMORY MAP AND STACK FOR THE PIC10F200/204





FIGURE 4-4:

PIC10F202/206 REGISTER FILE MAP

File Address		
00h	INDF ⁽¹⁾	
01h	TMR0	
02h	PCL	
03h	STATUS	
04h	FSR	
05h	OSCCAL	
06h	GPIO	
07h	CMCON0 ⁽²⁾	
08h		
	General Purpose Registers	
1Fh		
Note 1: Not a "Indire FSR R 2: PIC10F PIC10F	physical register. S ct Data Addressi egisters". F206 only. Unimple F202 and reads as 0	See Section 4.9 ing: INDF and emented on the 00h.

4.3.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers (SFRs) are registers used by the CPU and peripheral functions to control the operation of the device (Table 4-1).

The Special Function Registers can be classified into two sets. The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

TABLE 4-1: SPECIAL FUNCTION REGISTER (SFR) SUMMARY (PIC10F200/202/204/206)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset ⁽²⁾	Register on Page
00h	INDF	Uses Cont	ents of FSF	R to Add	ress Data Me	emory (not	a physica	l register)		xxxx xxxx	19
01h	TMR0	8-bit Real-	Time Clock	/Counter	r					XXXX XXXX	23, 27
02h ⁽¹⁾	PCL	Low-order	8 bits of PC)						1111 1111	18
03h	STATUS	GPWUF	CWUF ⁽⁵⁾	—	TO	PD	Z	DC	С	00-1 1xxx (3)	15
04h	FSR	Indirect Da	ata Memory	Address	s Pointer					111x xxxx	19
05h	OSCCAL	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	FOSC4	1111 1110	17
06h	GPIO	—	_		—	GP3	GP2	GP1	GP0	xxxx	20
07h ⁽⁴⁾	CMCON0	CMPOUT	COUTEN	POL	CMPT0CS	CMPON	CNREF	CPREF	CWU	1111 1111	28
N/A	TRISGPIO	_	_	_	_	I/O Contro	ol Registe	r		1111	31
N/A	OPTION	GPWU	GPPU	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	16

Legend: -= unimplemented, read as '0', x = unknown, u = unchanged, q = value depends on condition.

Note 1: The upper byte of the Program Counter is not directly accessible. See **Section 4.7** "**Program Counter**" for an explanation of how to access these bits.

2: Other (non Power-up) Resets include external Reset through MCLR, Watchdog Timer and wake-up on pin change Reset.

3: See Table 9-1 for other Reset specific values.

4: PIC10F204/206 only.

5: PIC10F204/206 only. On all other devices, this bit is reserved and should not be used.

4.5 **OPTION Register**

The OPTION register is a 8-bit wide, write-only register, which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W register will be transferred to the OPTION register. A Reset sets the OPTION<7:0> bits.

REGISTER 4-2: OPTION REGISTER

Note:	If TRIS bit is set to '0', the wake-up on
	change and pull-up functions are disabled
	for that pin (i.e., note that TRIS overrides
	Option control of GPPU and GPWU).

Note: If the TOCS bit is set to '1', it will override the TRIS function on the TOCKI pin.

W-1	W-1	W-1	W-1	W-1	W-1	W-1	W-1
GPWU	GPPU	T0CS	T0SE	PSA	PS2	PS1	PS0
bit 7 bit 0							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

1:16

1:32

1:64

1:128

bit 7	GPWU: Enable Wake-up on Pin Change bit (GP0, GP1, GP3)
	1 = Disabled 0 = Enabled
bit 6	GPPU: Enable Weak Pull-ups bit (GP0, GP1, GP3)
	1 = Disabled 0 = Enabled
bit 5	TOCS: Timer0 Clock Source Select bit
	1 = Transition on T0CKI pin (overrides TRIS on the T0CKI pin)0 = Transition on internal instruction cycle clock, Fosc/4
bit 4	T0SE: Timer0 Source Edge Select bit
	1 = Increment on high-to-low transition on the T0CKI pin0 = Increment on low-to-high transition on the T0CKI pin
bit 3	PSA: Prescaler Assignment bit
	1 = Prescaler assigned to the WDT0 = Prescaler assigned to Timer0
bit 2-0	PS<2:0>: Prescaler Rate Select bits
	Bit Value Timer0 Rate WDT Rate
	000 1:2 1:1 001 1:4 1:2 010 1:8 1:4 011 1:16 1:8

1:32

1:64

1 : 128 1 : 256

100

101

110 111

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)





Data Bus

FIGURE 9-2: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



FIGURE 9-3: TIME-OUT SEQUENCE ON POWER-UP (MCLR PULLED LOW)







FIGURE 9-9: BROWN-OUT PROTECTION CIRCUIT 3



9.9 Power-down Mode (Sleep)

A device may be powered-down (Sleep) and later powered-up (wake-up from Sleep).

9.9.1 SLEEP

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the TO bit (STATUS<4>) is set, the PD bit (STATUS<3>) is cleared and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, driving low or high-impedance).

Note:	A Reset generated by a WDT time-out
	does not drive the MCLR pin low.

For lowest current consumption while powered-down, the T0CKI input should be at VDD or Vss and the GP3/MCLR/VPP pin must be at a logic high level if MCLR is enabled.

9.9.2 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

- 1. An external Reset input on GP3/MCLR/VPP pin, when configured as MCLR.
- 2. A Watchdog Timer time-out Reset (if WDT was enabled).
- 3. A change on input pin GP0, GP1 or GP3 when wake-up on change is enabled.
- 4. A comparator output change has occurred when wake-up on comparator change is enabled.

These events cause a device Reset. The $\overline{\text{TO}}$, $\overline{\text{PD}}$ GPWUF and CWUF bits can be used to determine the cause of device Reset. The $\overline{\text{TO}}$ bit is cleared if a WDT time-out occurred (and caused wake-up). The $\overline{\text{PD}}$ bit, which is set on power-up, is cleared when SLEEP is invoked. The GPWUF bit indicates a change in state while in Sleep at pins GP0, GP1 or GP3 (since the last file or bit operation on GP port). The CWUF bit indicates a change in the state while in Sleep of the comparator output.

Caution:	Right before entering Sleep, read the input pins. When in Sleep, wake-up
	occurs when the values at the pins
	change from the state they were in at the
	last reading. If a wake-up on change
	occurs and the pins are not read before
	re-entering Sleep, a wake-up will occur
	immediately even if no pins change
	while in Sleep mode.

Note: The WDT is cleared when the device wakes from Sleep, regardless of the wake-up source.

Mnemonic,		Description	Cyclos	12-Bit Opcode			Status	Notos
Opera	nds	Description	Cycles	MSb		LSb	Affected	Notes
ADDWF	f, d	Add W and f	1	0001	11df	ffff	C, DC, Z	1, 2, 4
ANDWF	f, d	AND W with f	1	0001	01df	ffff	Z	2, 4
CLRF	f	Clear f	1	0000	011f	ffff	Z	4
CLRW	—	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	2, 4
DECFSZ	f, d	Decrement f, Skip if 0	1 ⁽²⁾	0010	11df	ffff	None	2, 4
INCF	f, d	Increment f	1	0010	10df	ffff	Z	2, 4
INCFSZ	f, d	Increment f, Skip if 0	1 ⁽²⁾	0011	11df	ffff	None	2, 4
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	2, 4
MOVF	f, d	Move f	1	0010	00df	ffff	Z	2, 4
MOVWF	f	Move W to f	1	0000	001f	ffff	None	1, 4
NOP	—	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	С	2, 4
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	С	2, 4
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C, DC, Z	1, 2, 4
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	2, 4
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	2, 4
		BIT-ORIENTED FILE REGISTE		ATIONS				
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	2, 4
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	2, 4
BTFSC	f, b	Bit Test f, Skip if Clear	1 ⁽²⁾	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 ⁽²⁾	0111	bbbf	ffff	None	
		LITERAL AND CONTROL C	PERATIO	ONS			L	
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	
CALL	k	Call Subroutine	2	1001	kkkk	kkkk	None	1
CLRWDT		Clear Watchdog Timer	1	0000	0000	0100	TO, PD	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	1100	kkkk	kkkk	None	
OPTION	_	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	_	Go into Standby mode	1	0000	0000	0011	TO, PD	
TRIS	f	Load TRIS register	1	0000	0000	Offf	None	3
XORLW	k	Exclusive OR literal to W	1	1111	kkkk	kkkk	Z	

TABLE 10-2: INSTRUCTION SET SUMMARY

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO. See Section 4.7 "Program Counter".

2: When an I/O register is modified as a function of itself (e.g. MOVF PORTB, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction TRIS f, where f = 6, causes the contents of the W register to be written to the tri-state latches of PORTB. A '1' forces the pin to a high-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).

IORWF	Inclusive OR W with f						
Syntax:	[label] IORWF f,d						
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$						
Operation:	(W).OR. (f) \rightarrow (dest)						
Status Affected:	Z						
Description:	Inclusive OR the W register with register 'f'. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed back in register 'f'.						

MOVWF	Move W to f					
Syntax:	[label] MOVWF f					
Operands:	$0 \leq f \leq 31$					
Operation:	$(W) \rightarrow (f)$					
Status Affected:	None					
Description:	Move data from the W register to register 'f'.					

MOVF	Move f						
Syntax:	[label] MOVF f,d						
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in [0,1] \end{array}$						
Operation:	$(f) \rightarrow (dest)$						
Status Affected:	Z						
Description:	The contents of register 'f' are moved to destination 'd'. If 'd' is '0', destination is the W register. If 'd' is '1', the destination is file register 'f'. 'd' = 1 is useful as a test of a file register, since status flag Z is affected.						

NOP	No Operation
Syntax:	[label] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

MOVLW	Move literal to W					
Syntax:	[<i>label</i>] MOVLW k					
Operands:	$0 \le k \le 255$					
Operation:	$k \rightarrow (W)$					
Status Affected:	None					
Description:	The 8-bit literal 'k' is loaded into the W register. The "don't cares" will assembled as '0's.					

OPTION	Load OPTION Register					
Syntax:	[label] OPTION					
Operands:	None					
Operation:	$(W) \rightarrow Option$					
Status Affected:	None					
Description:	The content of the W register is loaded into the OPTION register.					

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings^(†)

Ambient temperature under bias	40°C to +125°C
Storage temperature	65°C to +150°C
Voltage on VDD with respect to VSS	0 to +6.5V
Voltage on MCLR with respect to Vss	0 to +13.5V
Voltage on all other pins with respect to Vss	0.3V to (VDD + 0.3V)
Total power dissipation ⁽¹⁾	800 mW
Max. current out of Vss pin	80 mA
Max. current into Vod pin	80 mA
Input clamp current, Iк (Vi < 0 or Vi > VDD)	±20 mA
Output clamp current, Iок (Vo < 0 or Vo > Voo)	±20 mA
Max. output current sunk by any I/O pin	25 mA
Max. output current sourced by any I/O pin	25 mA
Max. output current sourced by I/O port	75 mA
Max. output current sunk by I/O port	75 mA
Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD $-\Sigma$ IOH} + Σ {(VDD	$(VOL \times IOH) + \sum (VOL \times IOL)$

[†]NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 12-4: RESET, WATCHDOG TIMER AND DEVICE RESET TIMER – PIC10F200/202/204/206

AC CHARACTERISTICS			$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise specified)}\\ \mbox{Operating Temperature} & -40^\circ C \leq TA \leq +85^\circ C \ (industrial)\\ & -40^\circ C \leq TA \leq +125^\circ C \ (extended) \end{array} \\ \mbox{Operating Voltage VDD range is described in Section 12.1 "DC Characteristics: PIC10F200/202/204/206 (Industrial)"} \end{array}$					
Param. No.	Sym.	Characteristic	Min. Typ. ⁽¹⁾ Max. Units Conditions					
30	TMCL	MCLR Pulse Width (low)	2* 5*	_		μs μs	VDD = 5V, -40°C to +85°C VDD = 5.0V	
31	Twdt	Watchdog Timer Time-out Period (no prescaler)	10 10	16 16	29 31	ms ms	VDD = 5.0V (industrial) VDD = 5.0V (extended)	
32	Tdrt	Device Reset Timer Period (standard)	10 10	16 16	29 31	ms ms	VDD = 5.0V (industrial) VDD = 5.0V (extended)	
34	Tioz	I/O High-impedance from MCLR low		_	2*	μS		

* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 12-4: TIMER0 CLOCK TIMINGS – PIC10F200/202/204/206



TABLE 12-5: TIMER0 CLOCK REQUIREMENTS - PIC10F200/202/204/206

AC CHARACTERISTICS		Standard Operating Conditions (unless otherwise specified)Operating Temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ (industrial) $-40^{\circ}C \le TA \le +125^{\circ}C$ (extended)Operating Voltage VDD range is described inSection 12.1 "DC Characteristics: PIC10F200/202/204/206 (Industrial)".						
Param. No.	Varam. No. Sym. Characteristic			Min.	Тур. ⁽¹⁾	Max.	Units	Conditions
40	Tt0H	H TOCKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	_	ns	
			With Prescaler	10*		—	ns	
41	Tt0L T0CKI Low Pulse		No Prescaler	0.5 TCY + 20*	—		ns	
		Width	With Prescaler	10*		_	ns	
42	Tt0P	TOCKI Period		20 or $\frac{T_{CY} + 40^*}{N}$			ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ.") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

















FIGURE 13-11: VOH vs. IOH OVER TEMPERATURE (VDD = 5.0V)



FIGURE 13-10: VOH vs. IOH OVER TEMPERATURE (VDD = 3.0V)

8-Lead Plastic Dual Flat, No Lead Package (MC) – 2x3x0.9 mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS					
Dimensio	n Limits	MIN	MIN NOM				
Number of Pins	Ν	8					
Pitch	е		0.50 BSC				
Overall Height	А	0.80	0.90	1.00			
Standoff	A1	0.00	0.02	0.05			
Contact Thickness	A3	0.20 REF					
Overall Length	D	2.00 BSC					
Overall Width	E		3.00 BSC				
Exposed Pad Length	D2	1.30	-	1.55			
Exposed Pad Width	E2	1.50	-	1.75			
Contact Width	b	0.20	0.25	0.30			
Contact Length	L	0.30	0.40	0.50			
Contact-to-Exposed Pad	К	0.20	-	-			

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package may have one or more exposed tie bars at ends.
- 3. Package is saw singulated.
- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-123C